

SOT618-17(D)

HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.9 mm body

14 January 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-10-2019
Manufacturer package code	98ASA01504D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
seated height	0.8	0.9	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	



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2 Package outline

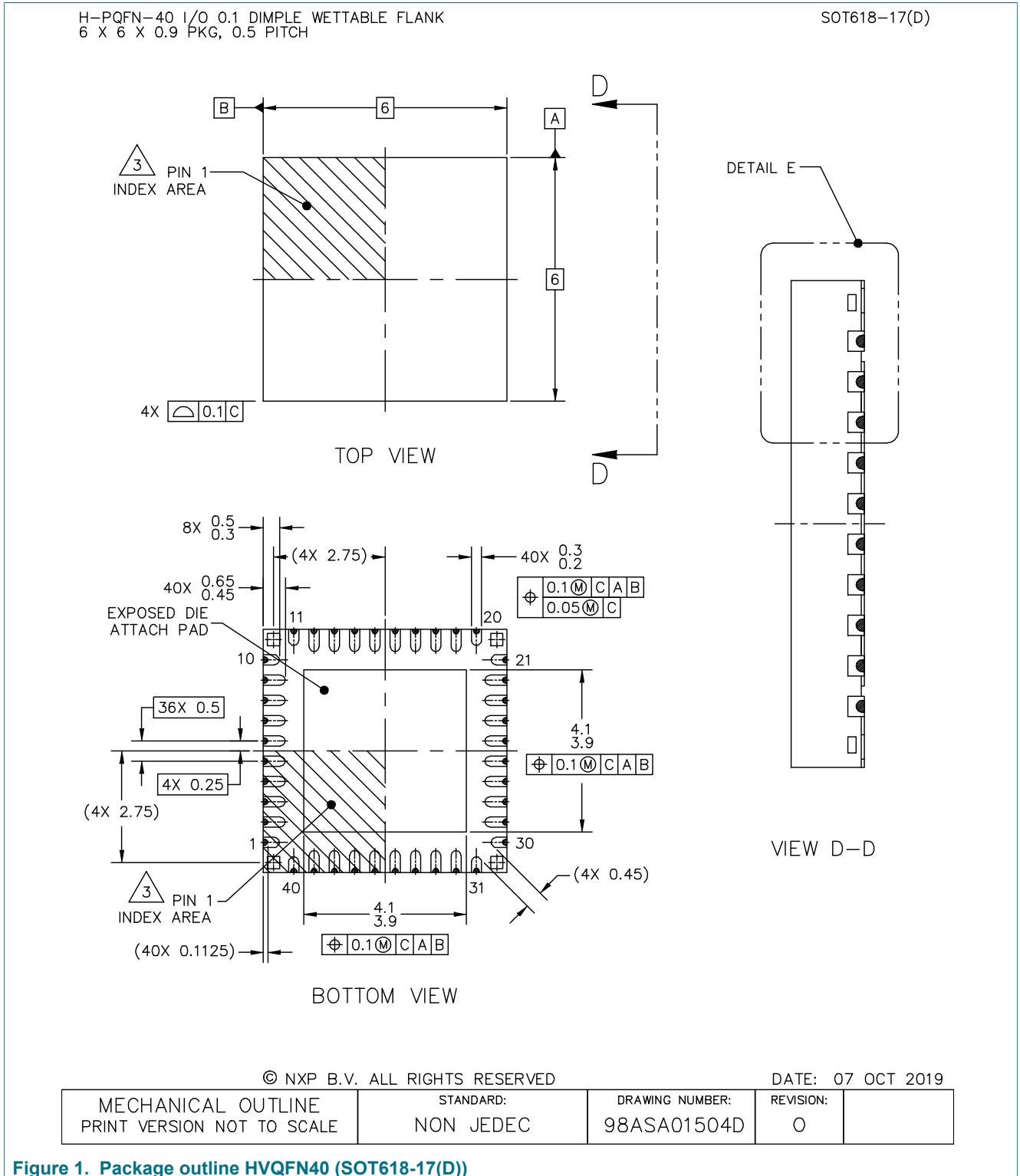
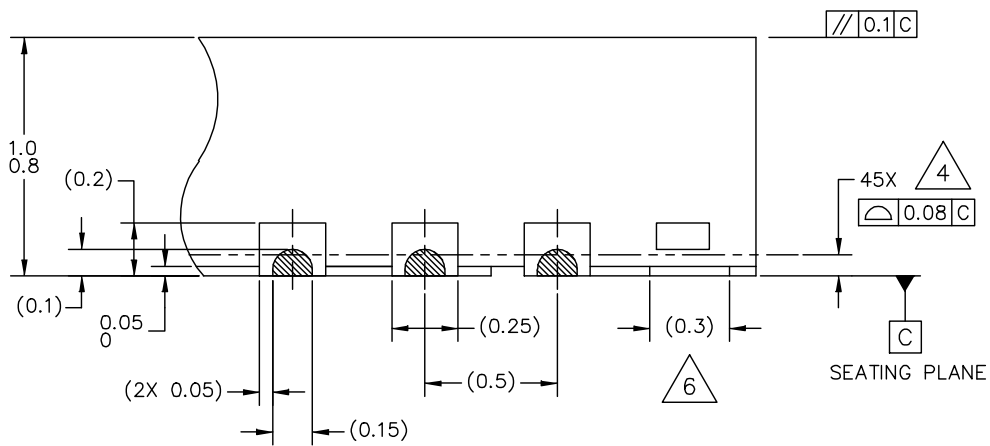


Figure 1. Package outline HVQFN40 (SOT618-17(D))

HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.9 mm body

H-PQFN-40 I/O 0.1 DIMPLE WETTABLE FLANK
6 X 6 X 0.9 PKG, 0.5 PITCH

SOT618-17(D)



DETAIL E
VIEW ROTATED 90° CW

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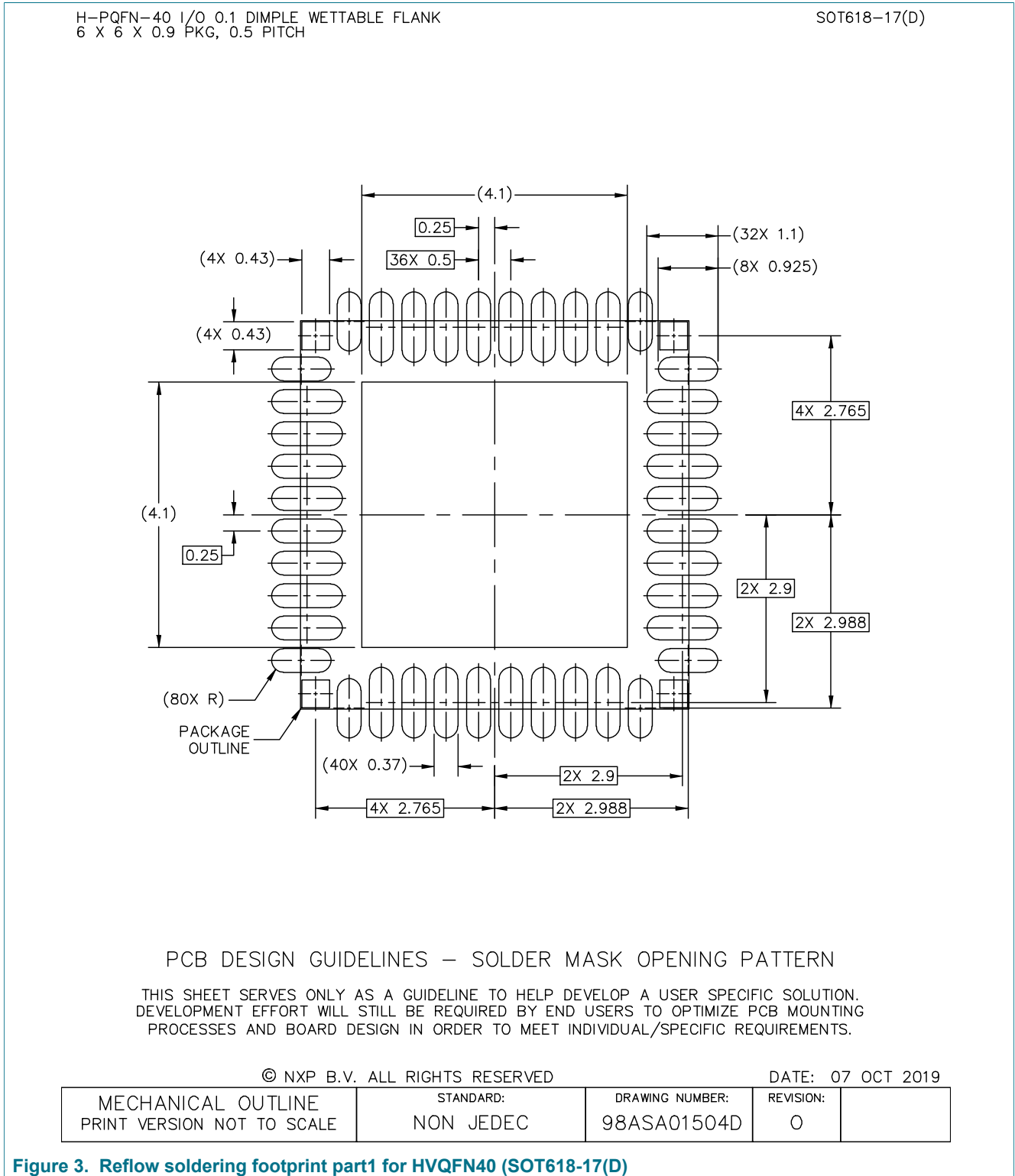
DATE: 07 OCT 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01504D	REVISION: 0	
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Figure 2. Package outline detail HVQFN40 (SOT618-17(D))

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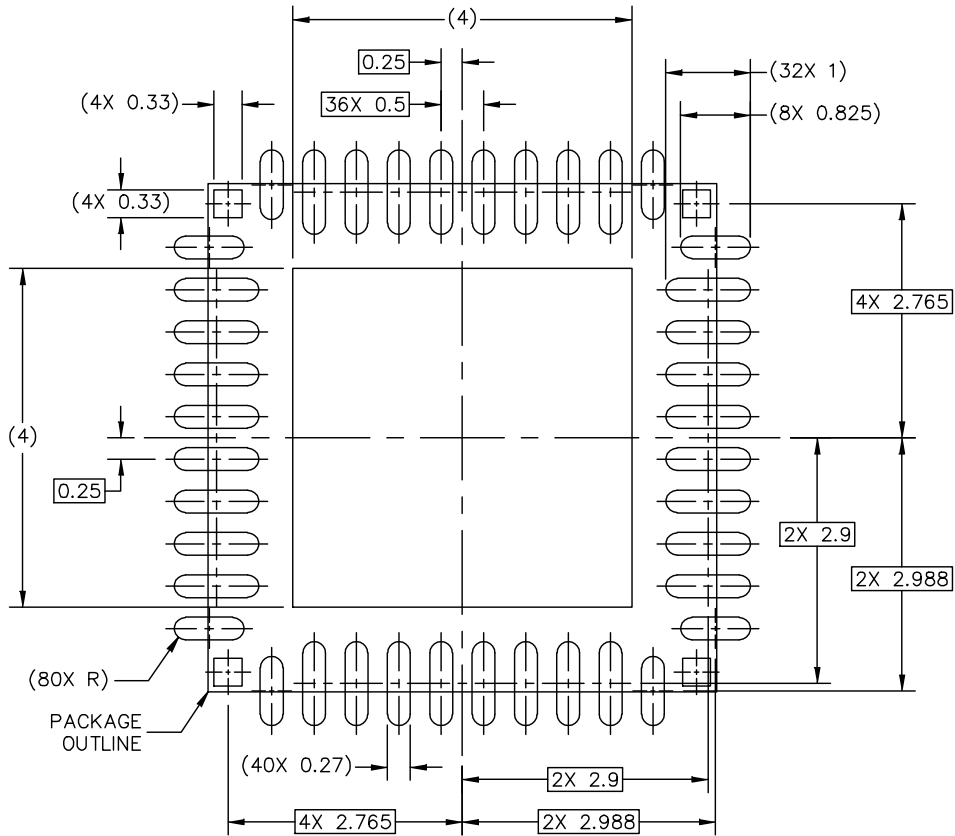
3 Soldering



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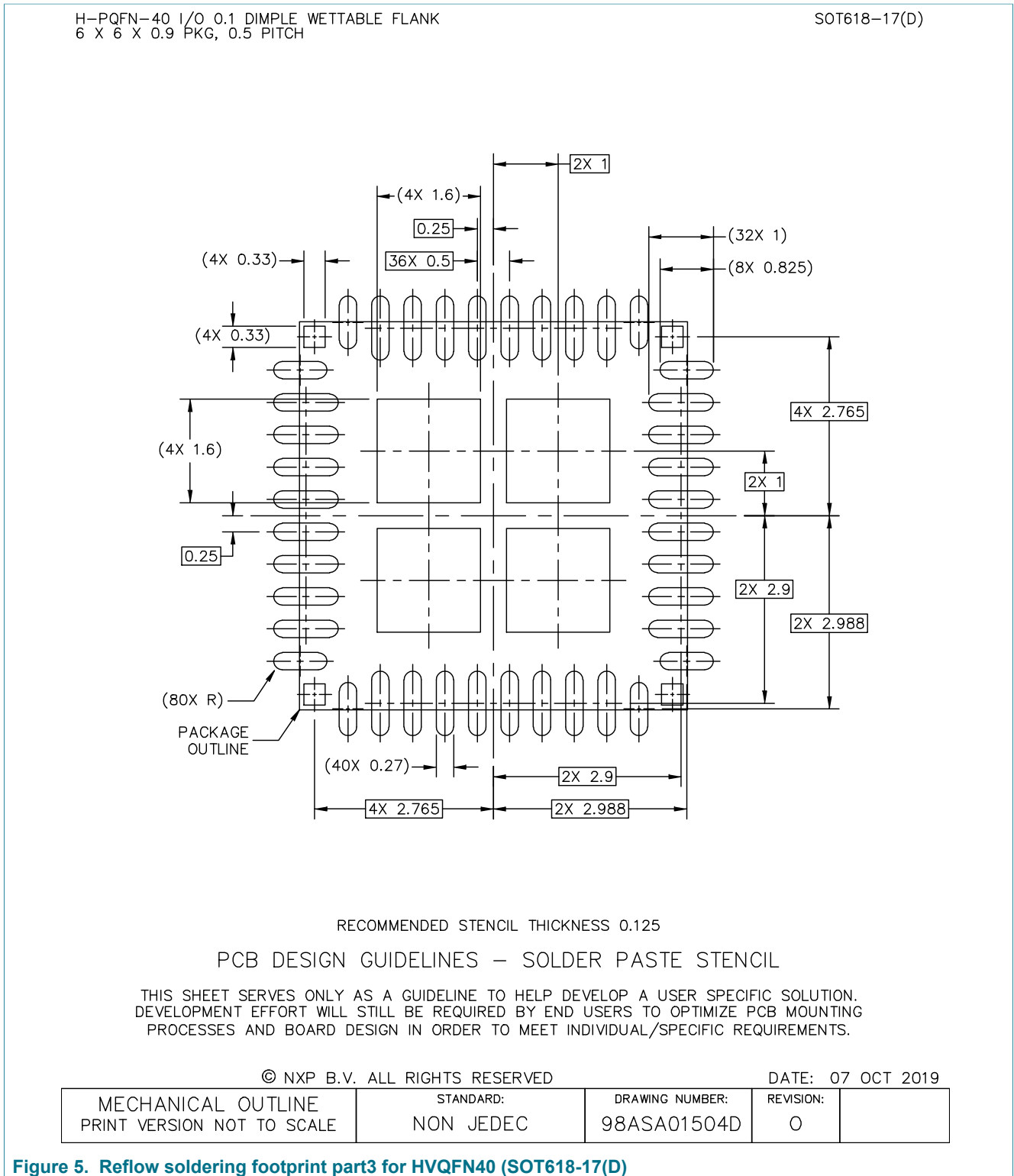
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Figure 4. Reflow soldering footprint part2 for HVQFN40 (SOT618-17(D))

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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Figure 6. Package outline note HVQFN40 (SOT618-17(D))

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